

General description

The SLESD5Z12C is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time , make these parts ideal for ESD protection on designs where board space is at a premium

Features and benefits

- Reverse stand-off voltage: 12V Max
- Low leakage current: nA Level
- Low Clamping Voltage: $V_C \leq 17\text{ V@}9\text{A}(8/20\mu\text{s})$
- Response time is typically $< 1\text{ ns}$
- IEC61000-4-2 Level 4 ESD Protection

Application information

- Cell phones
- Audio equipment
- Portable devices
- Digital cameras
- Power supplies

Ordering information

Device	Package	Packaging	Reel Size
SLESD5Z12C	SOD523	3000/Tape & Reel	7 inch

Schematic & Pin configuration

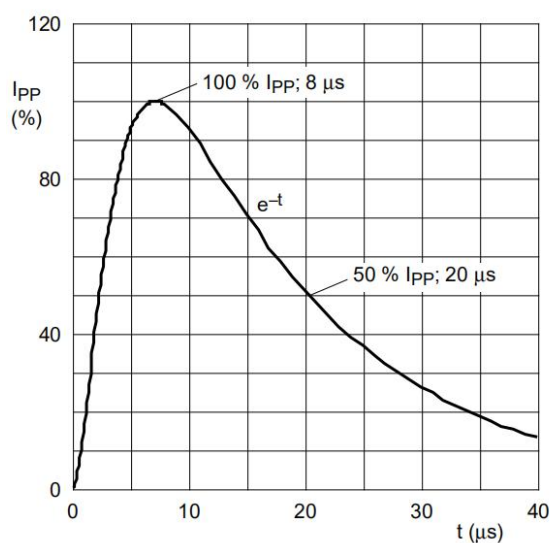
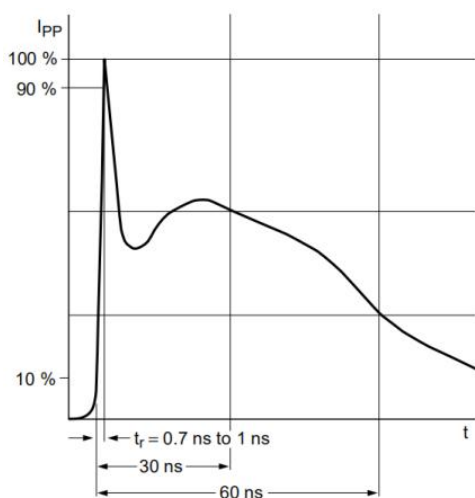
Simplified outline	Graphic symbol

Maximum Ratings ($T_{OP} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power ($t_p = 8/20\text{ }\mu\text{s}$)	P_{PPM}	160	W
Peak Pulse Current ($t_p = 8/20\text{ }\mu\text{s}$)	I_{PPM}	9	A
Maximum lead temperature for soldering during 10s	T_L	260	$^{\circ}\text{C}$
Storage Temperature Range	T_{stg}	-55 to +150	$^{\circ}\text{C}$
Operating Temperature Range	T_{OP}	-40 to +125	$^{\circ}\text{C}$
Maximum junction temperature	T_j	150	$^{\circ}\text{C}$
ESD voltage IEC 61000-4-2 (air discharge)	V_{ESD}	30	kV
ESD voltage IEC 61000-4-2 (contact discharge)	V_{ESD}	30	kV

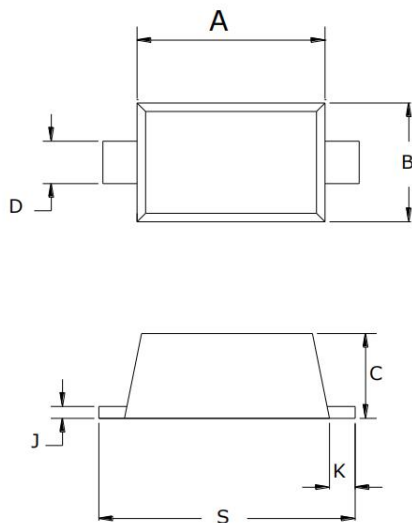
Electrical Characteristics ($T_{OP} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Condition
Reverse Working Voltage	V_{RWM}	--	--	12.0	V	
Breakdown Voltage	V_{BR}	13.0	--	16	V	$I_T=1\text{mA}$
Leakage Current I_{Leak}	I_R	--	--	200	nA	$V_{RWM}=12\text{V}$
Clamping Voltage	V_C	--	17	18	V	$I_{PP}=9\text{A}, t_p=8/20\mu\text{s}$
Junction Capacitance	C_j	--	8	10	pF	$V_R=0\text{V}, f=1\text{MHz}$



Package Outline Dimensions

SOD523



SYMBOL	Dimensions In Millimet	
	MIN	MAX
A	1.10	1.30
B	0.70	0.90
C	0.50	0.70
D	0.25	0.35
J	0.07	0.20
K	0.15	0.25
S	1.50	1.70

Soldering Footprint (mm)

